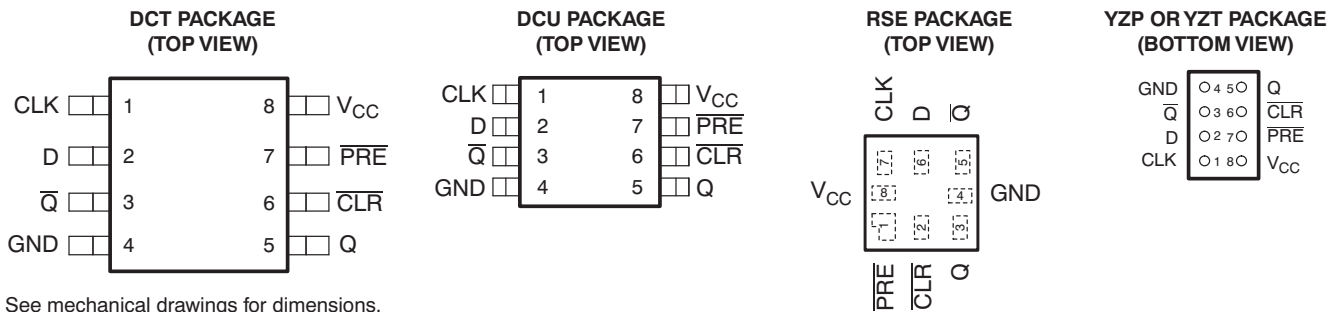


FEATURES

- Available in the Texas Instruments NanoFree™ Package
- Optimized for 1.8-V Operation and Is 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- I_{off} Supports Partial-Power-Down Mode Operation
- Sub-1-V Operable
- Max t_{pd} of 1.5 ns at 1.8 V
- Low Power Consumption, 10- μ A Max I_{CC}
- ± 8 -mA Output Drive at 1.8 V
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)



DESCRIPTION/ORDERING INFORMATION

This single positive-edge-triggered D-type flip-flop is operational at 0.8-V to 2.7-V V_{CC} , but is designed specifically for 1.65-V to 1.95-V V_{CC} operation.

A low level at the preset (\overline{PRE}) or clear (\overline{CLR}) input sets or resets the outputs, regardless of the levels of the other inputs. When \overline{PRE} and \overline{CLR} are inactive (high), data at the data (D) input meeting the setup time requirements is transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not related directly to the rise time of the clock pulse. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs. To better optimize the flip-flop for higher frequencies, the \overline{CLR} input overrides the \overline{PRE} input when they are both low.

NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoFree is a trademark of Texas Instruments.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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SN74AUC1G74

SINGLE POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH CLEAR AND PRESET

SCES537D–DECEMBER 2003–REVISED JUNE 2007

ORDERING INFORMATION

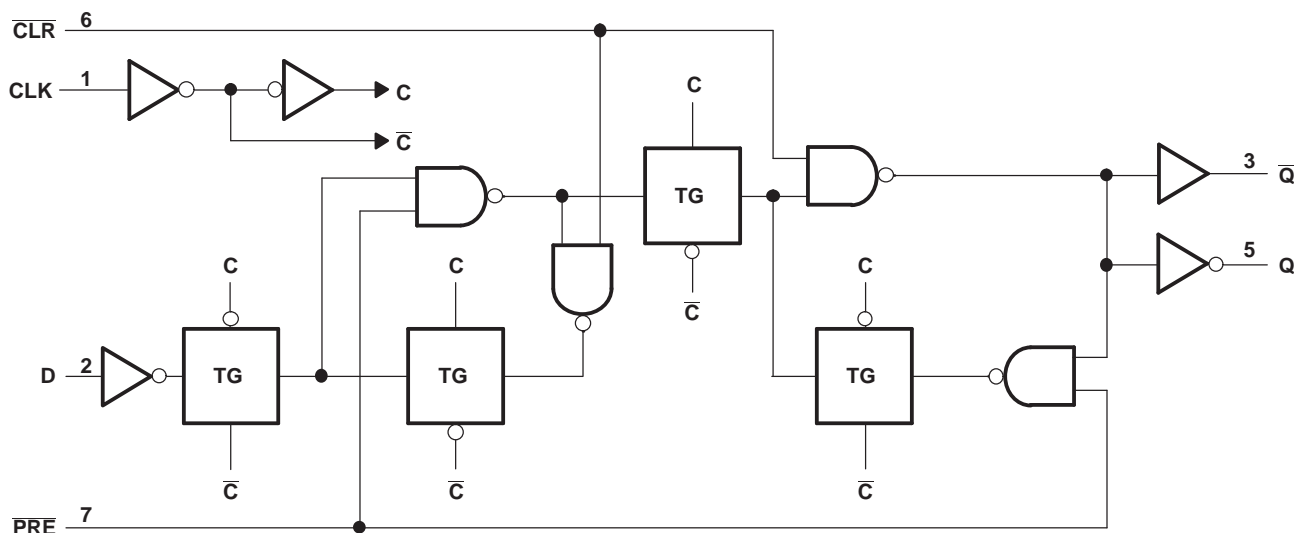
| T _A | PACKAGE ⁽¹⁾⁽²⁾ | | ORDERABLE PART NUMBER | TOP-SIDE MARKING ⁽³⁾ |
|----------------|--|--------------|-----------------------|---------------------------------|
| –40°C to 85°C | NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free) | Reel of 3000 | SN74AUC1G74YZPR | ___UP__ |
| | NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZT (Pb-free) | Reel of 3000 | SN74AUC1G74YZTR | |
| | QFN – RSE | Reel of 3000 | SN74AUC1G74RSER | UP |
| | SSOP – DCT | Reel of 3000 | SN74AUC1G74DCTR | U74___ |
| | VSSOP – DCU | Reel of 3000 | SN74AUC1G74DCUR | U74_ |

- (1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.
- (2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.
- (3) DCT: The actual top-side marking has three additional characters that designate the year, month, and assembly/test site.
DCU: The actual top-side marking has one additional character that designates the assembly/test site.
YZP/YZT: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).

FUNCTION TABLE

| INPUTS | | | | OUTPUTS | |
|--------|-----|-----|---|----------------|-------------|
| PRE | CLR | CLK | D | Q | \bar{Q} |
| L | H | X | X | H | L |
| X | L | X | X | L | H |
| H | H | ↑ | H | H | L |
| H | H | ↑ | L | L | H |
| H | H | L | X | Q ₀ | \bar{Q}_0 |

LOGIC DIAGRAM (POSITIVE LOGIC)



A. Pin numbers shown are for the DCT, DCU, YZP, and YZT packages only.

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

| | | MIN | MAX | UNIT |
|------------------|---|--------------------|-----------------------|------|
| V _{CC} | Supply voltage range | –0.5 | 3.6 | V |
| V _I | Input voltage range ⁽²⁾ | –0.5 | 3.6 | V |
| V _O | Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾ | –0.5 | 3.6 | V |
| V _O | Output voltage range ⁽²⁾ | –0.5 | V _{CC} + 0.5 | V |
| I _{IK} | Input clamp current | V _I < 0 | –50 | mA |
| I _{OK} | Output clamp current | V _O < 0 | –50 | mA |
| I _O | Continuous output current | | ±20 | mA |
| | Continuous current through V _{CC} or GND | | ±100 | mA |
| θ _{JA} | Package thermal impedance ⁽³⁾ | DCT package | 220 | °C/W |
| | | DCU package | 227 | |
| | | RSE package | 253 | |
| | | YZP/YZT package | 102 | |
| T _{stg} | Storage temperature range | –65 | 150 | °C |

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JEDEC 51-7.

Recommended Operating Conditions⁽¹⁾

| | | MIN | MAX | UNIT |
|-----------------|------------------------------------|--|------------------------|------|
| V _{CC} | Supply voltage | 0.8 | 2.7 | V |
| V _{IH} | High-level input voltage | V _{CC} = 0.8 V | V _{CC} | V |
| | | V _{CC} = 1.1 V to 1.95 V | 0.65 × V _{CC} | |
| | | V _{CC} = 2.3 V to 2.7 V | 1.7 | |
| V _{IL} | Low-level input voltage | V _{CC} = 0.8 V | 0 | V |
| | | V _{CC} = 1.1 V to 1.95 V | 0.35 × V _{CC} | |
| | | V _{CC} = 2.3 V to 2.7 V | 0.7 | |
| V _I | Input voltage | 0 | 3.6 | V |
| V _O | Output voltage | 0 | V _{CC} | V |
| I _{OH} | High-level output current | V _{CC} = 0.8 V | –0.7 | mA |
| | | V _{CC} = 1.1 V | –3 | |
| | | V _{CC} = 1.4 V | –5 | |
| | | V _{CC} = 1.65 V | –8 | |
| | | V _{CC} = 2.3 V | –9 | |
| I _{OL} | Low-level output current | V _{CC} = 0.8 V | 0.7 | mA |
| | | V _{CC} = 1.1 V | 3 | |
| | | V _{CC} = 1.4 V | 5 | |
| | | V _{CC} = 1.65 V | 8 | |
| | | V _{CC} = 2.3 V | 9 | |
| Δt/Δv | Input transition rise or fall rate | V _{CC} = 0.8 V to 1.65 V ⁽²⁾ | 20 | ns/V |
| | | V _{CC} = 1.65 V to 2.3 V ⁽³⁾ | 20 | |
| | | V _{CC} = 2.3 V to 2.7 V ⁽³⁾ | 20 | |
| T _A | Operating free-air temperature | –40 | 85 | °C |

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.
- (2) The data was taken at C_L = 15 pF, R_L = 2 kΩ (see Figure 1).
- (3) The data was taken at C_L = 30 pF, R_L = 500 Ω (see Figure 1).

SN74AUC1G74

SINGLE POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH CLEAR AND PRESET

SCES537D–DECEMBER 2003–REVISED JUNE 2007

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | V _{CC} | MIN | TYP ⁽¹⁾ | MAX | UNIT |
|------------------|------------|---|-----------------|-----------------------|--------------------|------|------|
| V _{OH} | | I _{OH} = −100 μA | 0.8 V to 2.7 V | V _{CC} − 0.1 | | | V |
| | | I _{OH} = −0.7 mA | 0.8 V | 0.55 | | | |
| | | I _{OH} = −3 mA | 1.1 V | 0.8 | | | |
| | | I _{OH} = −5 mA | 1.4 V | 1 | | | |
| | | I _{OH} = −8 mA | 1.65 V | 1.2 | | | |
| | | I _{OH} = −9 mA | 2.3 V | 1.8 | | | |
| V _{OL} | | I _{OL} = 100 μA | 0.8 V to 2.7 V | | | 0.2 | V |
| | | I _{OL} = 0.7 mA | 0.8 V | 0.25 | | | |
| | | I _{OL} = 3 mA | 1.1 V | | | 0.3 | |
| | | I _{OL} = 5 mA | 1.4 V | | | 0.4 | |
| | | I _{OL} = 8 mA | 1.65 V | | | 0.45 | |
| | | I _{OL} = 9 mA | 2.3 V | | | 0.6 | |
| I _I | All inputs | V _I = V _{CC} or GND | 0 to 2.7 V | | | 5 | μA |
| I _{off} | | V _I or V _O = 2.7 V | 0 | | | ±10 | μA |
| I _{CC} | | V _I = V _{CC} or GND, I _O = 0 | 0.8 V to 2.7 V | | | 10 | μA |
| C _I | | V _I = V _{CC} or GND | 2.5 V | 2.5 | | | pF |

(1) All typical values are at T_A = 25°C.

Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 1](#))

| | | V _{CC} = 0.8 V | V _{CC} = 1.2 V ± 0.1 V | V _{CC} = 1.5 V ± 0.1 V | V _{CC} = 1.8 V ± 0.15 V | V _{CC} = 2.5 V ± 0.2 V | UNIT |
|--------------------|----------------------------|---|------------------------------------|------------------------------------|-------------------------------------|------------------------------------|------|
| | | TYP | MIN | MAX | MIN | MAX | |
| f _{clock} | Clock frequency | 50 | 200 | | 225 | | MHz |
| t _w | Pulse duration | CLK | 2 | 1 | 1 | 1 | ns |
| | | $\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ low | 5 | 1.5 | 1 | 1 | |
| t _{su} | Setup time before CLK↑ | Data | 2.2 | 0.6 | 0.5 | 0.5 | ns |
| | | $\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ inactive | 2.9 | 1.6 | 0.9 | 0.7 | |
| t _h | Hold time, data after CLK↑ | | 1.2 | 0.5 | 0.4 | 0.3 | ns |

Switching Characteristics

over recommended operating free-air temperature range, C_L = 15 pF (unless otherwise noted) (see [Figure 1](#))

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | V _{CC} = 0.8 V | V _{CC} = 1.2 V ± 0.1 V | | V _{CC} = 1.5 V ± 0.1 V | | V _{CC} = 1.8 V ± 0.15 V | | | V _{CC} = 2.5 V ± 0.2 V | | UNIT |
|------------------|--|----------------------------|-------------------------|------------------------------------|-----|------------------------------------|-----|-------------------------------------|-----|-----|------------------------------------|-----|------|
| | | | TYP | MIN | MAX | MIN | MAX | MIN | TYP | MAX | MIN | MAX | |
| f _{max} | | | 50 | 200 | | 225 | | 250 | | | 275 | | MHz |
| t _{pd} | CLK | Q | 10.3 | 1.7 | 3.7 | 1.2 | 2.5 | 1 | 1.2 | 1.7 | 0.8 | 1.2 | ns |
| | | $\overline{\text{Q}}$ | 9.6 | 1 | 3.8 | 1 | 3 | 0.9 | 1.1 | 1.5 | 0.7 | 1.1 | |
| | $\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ | Q or $\overline{\text{Q}}$ | 12.9 | 2 | 4.5 | 0.9 | 3.1 | 1.1 | 1.5 | 2.2 | 0.9 | 1.5 | |

Switching Characteristics

over recommended operating free-air temperature range, $C_L = 30$ pF (unless otherwise noted) (see [Figure 1](#))

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | $V_{CC} = 1.8\text{ V}$ $\pm 0.15\text{ V}$ | | | $V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$ | | UNIT |
|-----------|-------------------------|---------------------|--|-----|-----|---|-----|------|
| | | | MIN | TYP | MAX | MIN | MAX | |
| f_{max} | | | 250 | | | 275 | | ns |
| t_{pd} | CLK | Q | 1.5 | 1.9 | 2.4 | 1.4 | 1.8 | ns |
| | | \overline{Q} | 1.4 | 1.9 | 2.4 | 1.3 | 1.8 | |
| | PRE or \overline{CLR} | Q or \overline{Q} | 1.7 | 2.2 | 2.8 | 1.5 | 2.1 | |

Operating Characteristics

$T_A = 25^\circ\text{C}$

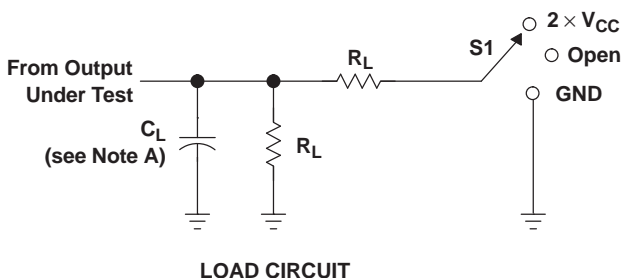
| PARAMETER | | TEST CONDITIONS | $V_{CC} = 0.8\text{ V}$ | $V_{CC} = 1.2\text{ V}$ | $V_{CC} = 1.5\text{ V}$ | $V_{CC} = 1.8\text{ V}$ | $V_{CC} = 2.5\text{ V}$ | UNIT |
|-----------|----------------------------------|---------------------|-------------------------|-------------------------|-------------------------|-------------------------|-------------------------|------|
| | | | TYP | TYP | TYP | TYP | TYP | |
| C_{pd} | Power dissipation capacitance | $f = 10\text{ MHz}$ | 35 | 36 | 39 | 44 | 59 | pF |

SN74AUC1G74

SINGLE POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH CLEAR AND PRESET

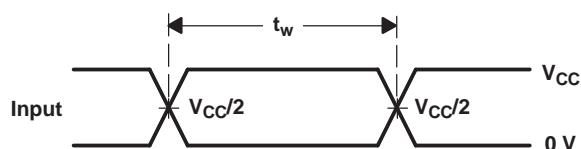
SCES537D–DECEMBER 2003–REVISED JUNE 2007

PARAMETER MEASUREMENT INFORMATION

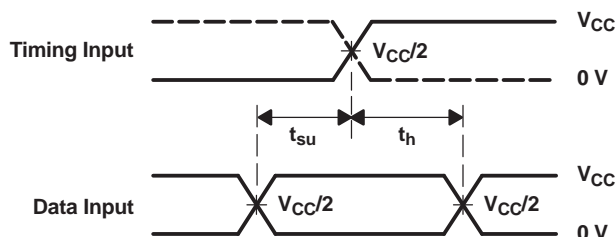


| TEST | S1 |
|-------------------|-------------------|
| t_{PLH}/t_{PHL} | Open |
| t_{PLZ}/t_{PZL} | $2 \times V_{CC}$ |
| t_{PHZ}/t_{PZH} | GND |

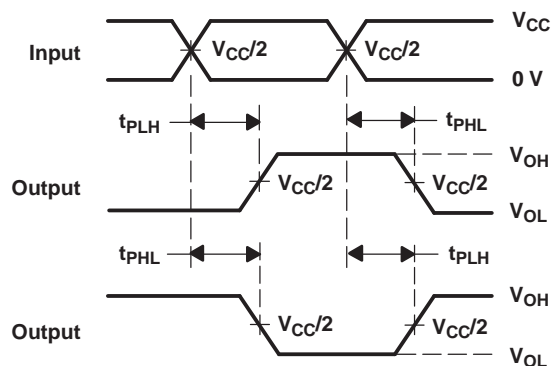
| V_{CC} | C_L | R_L | V_{Δ} |
|--------------------|-------|--------------|--------------|
| 0.8 V | 15 pF | 2 k Ω | 0.1 V |
| 1.2 V \pm 0.1 V | 15 pF | 2 k Ω | 0.1 V |
| 1.5 V \pm 0.1 V | 15 pF | 2 k Ω | 0.1 V |
| 1.8 V \pm 0.15 V | 15 pF | 2 k Ω | 0.15 V |
| 2.5 V \pm 0.2 V | 15 pF | 2 k Ω | 0.15 V |
| 1.8 V \pm 0.15 V | 30 pF | 1 k Ω | 0.15 V |
| 2.5 V \pm 0.2 V | 30 pF | 500 Ω | 0.15 V |



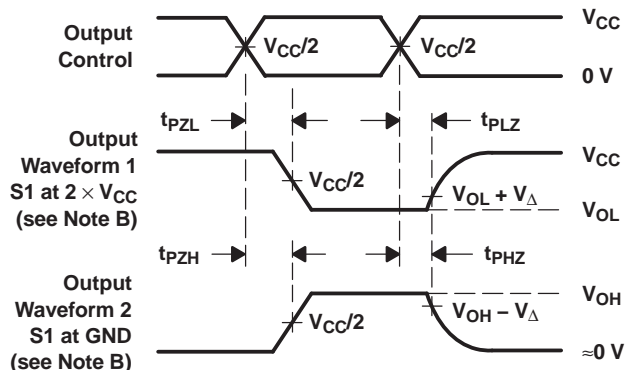
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, slew rate \geq 1 V/ns.
 - The outputs are measured one at a time, with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .
 - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|-------------------|---------------|--------------|-----------------|------|-------------|-----------------|--------------------------------------|----------------------|--------------|-------------------------|-------------------------|
| SN74AUC1G74DCTR | ACTIVE | SSOP | DCT | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | U74 Z | Samples |
| SN74AUC1G74DCUR | ACTIVE | VSSOP | DCU | 8 | 3000 | RoHS & Green | NIPDAU SN | Level-1-260C-UNLIM | -40 to 85 | (74, U74Q, U74R) UZ | Samples |
| SN74AUC1G74DCURE4 | ACTIVE | VSSOP | DCU | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | U74R | Samples |
| SN74AUC1G74DCURG4 | ACTIVE | VSSOP | DCU | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | U74R | Samples |
| SN74AUC1G74RSER | ACTIVE | UQFN | RSE | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | UP | Samples |
| SN74AUC1G74YZPR | ACTIVE | DSBGA | YZP | 8 | 3000 | RoHS & Green | SNAGCU | Level-1-260C-UNLIM | -40 to 85 | UPN | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74AUC1G74DCTR | SSOP | DCT | 8 | 3000 | 180.0 | 13.0 | 3.35 | 4.5 | 1.55 | 4.0 | 12.0 | Q3 |
| SN74AUC1G74DCUR | VSSOP | DCU | 8 | 3000 | 180.0 | 9.0 | 2.25 | 3.4 | 1.0 | 4.0 | 8.0 | Q3 |
| SN74AUC1G74DCURG4 | VSSOP | DCU | 8 | 3000 | 180.0 | 8.4 | 2.25 | 3.35 | 1.05 | 4.0 | 8.0 | Q3 |
| SN74AUC1G74RSER | UQFN | RSE | 8 | 3000 | 180.0 | 9.5 | 1.7 | 2.2 | 0.75 | 4.0 | 8.0 | Q2 |
| SN74AUC1G74YZPR | DSBGA | YZP | 8 | 3000 | 178.0 | 9.2 | 1.02 | 2.02 | 0.63 | 4.0 | 8.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

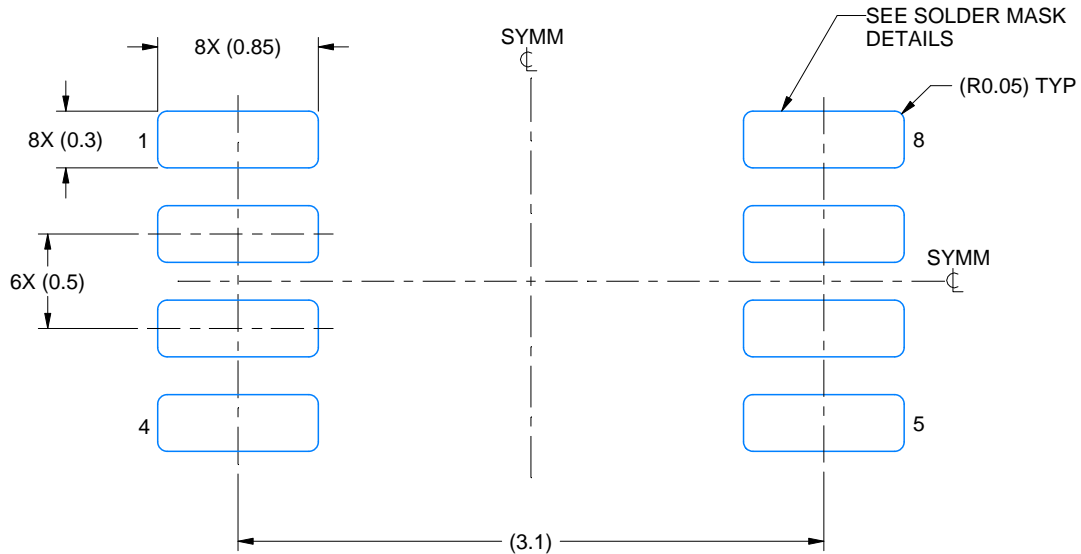
| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74AUC1G74DCTR | SSOP | DCT | 8 | 3000 | 182.0 | 182.0 | 20.0 |
| SN74AUC1G74DCUR | VSSOP | DCU | 8 | 3000 | 182.0 | 182.0 | 20.0 |
| SN74AUC1G74DCURG4 | VSSOP | DCU | 8 | 3000 | 202.0 | 201.0 | 28.0 |
| SN74AUC1G74RSER | UQFN | RSE | 8 | 3000 | 189.0 | 185.0 | 36.0 |
| SN74AUC1G74YZPR | DSBGA | YZP | 8 | 3000 | 220.0 | 220.0 | 35.0 |

EXAMPLE BOARD LAYOUT

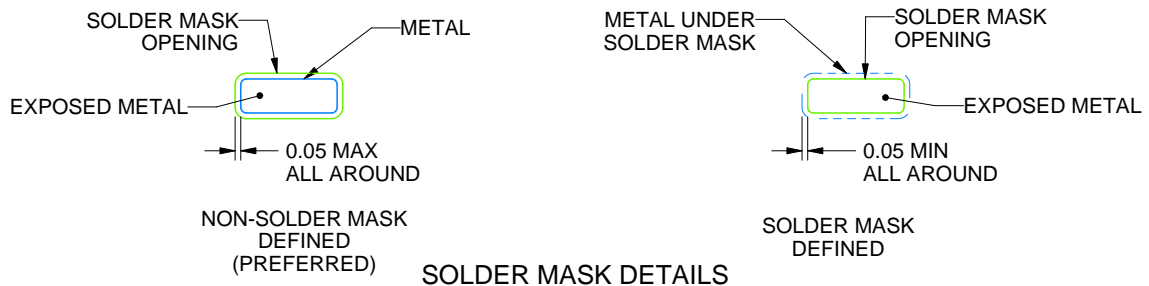
DCU0008A

VSSOP - 0.9 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 25X



4225266/A 09/2014

NOTES: (continued)

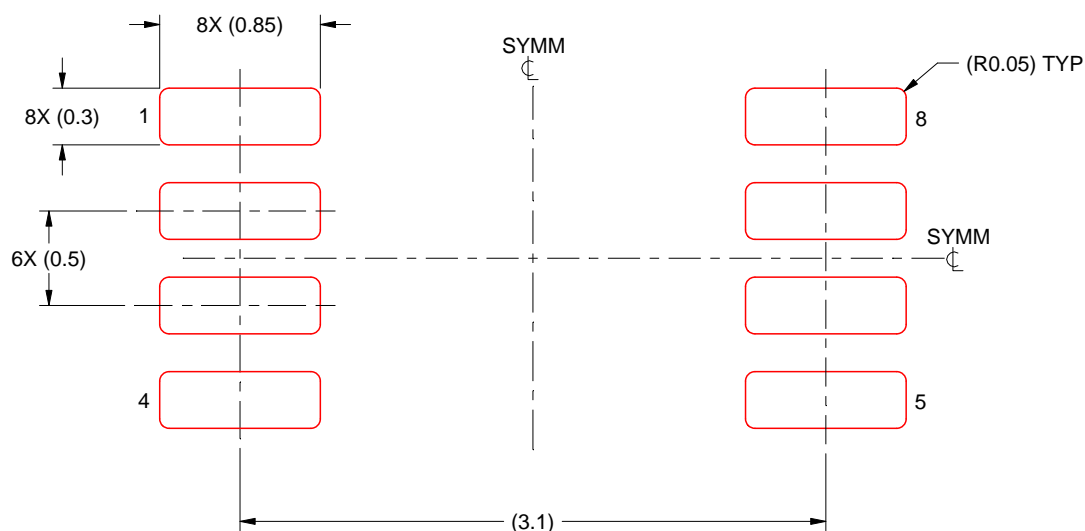
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DCU0008A

VSSOP - 0.9 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 25X

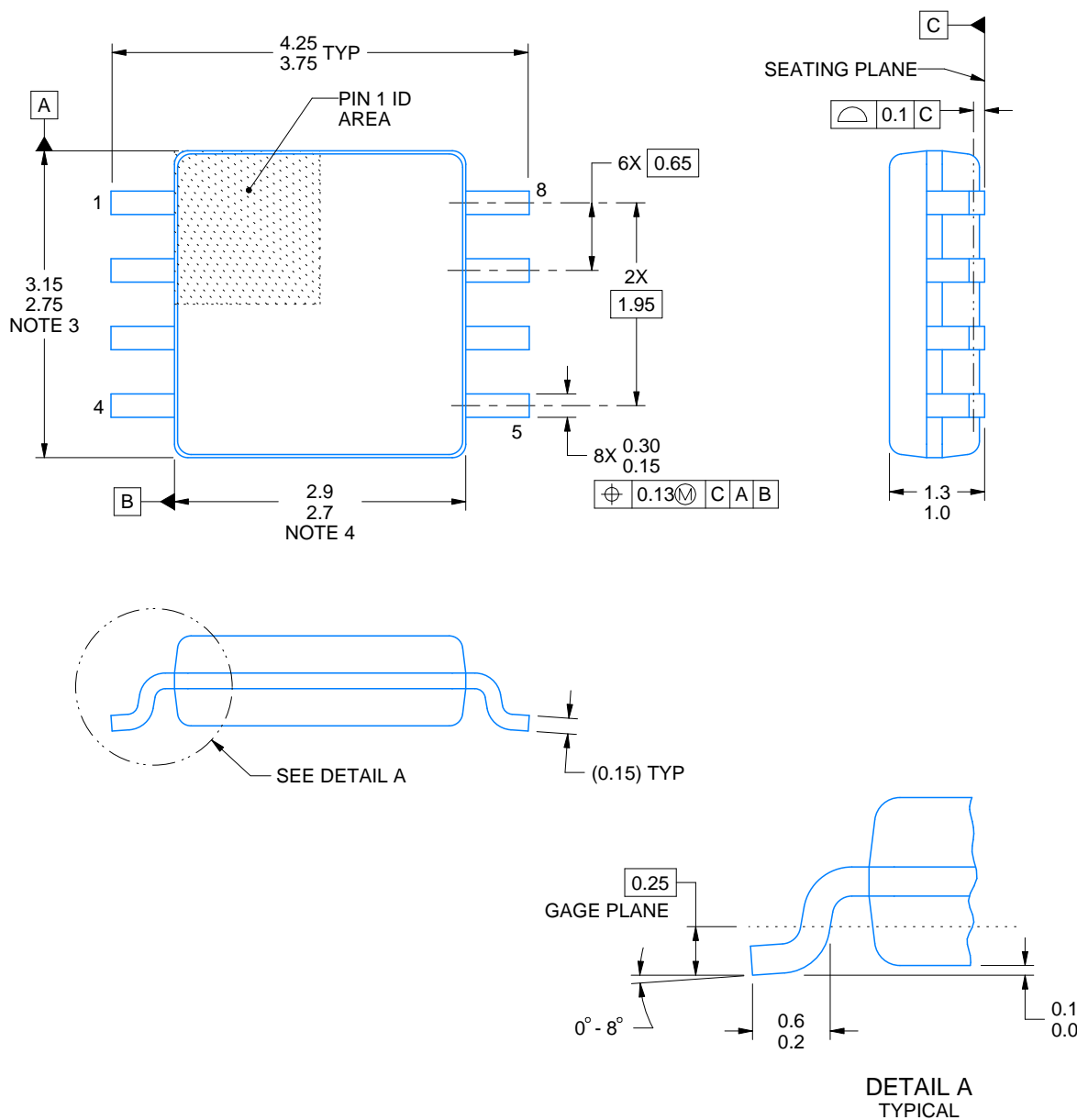
4225266/A 09/2014

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

DCT0008A**PACKAGE OUTLINE****SSOP - 1.3 mm max height**

SMALL OUTLINE PACKAGE



4220784/C 06/2021

NOTES:

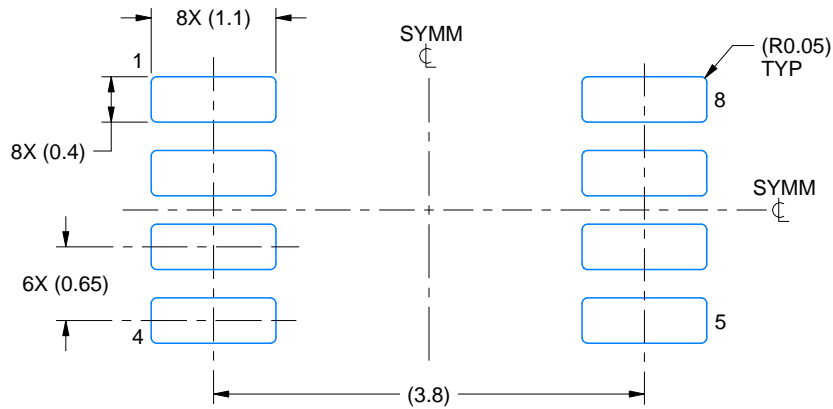
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.

EXAMPLE BOARD LAYOUT

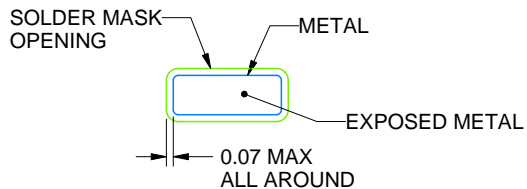
DCT0008A

SSOP - 1.3 mm max height

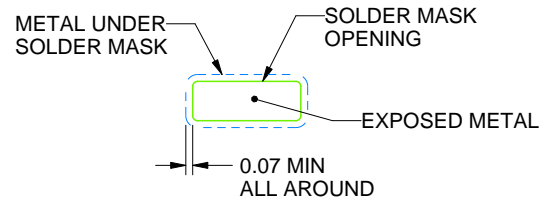
SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X



NON SOLDER MASK
DEFINED



SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4220784/C 06/2021

NOTES: (continued)

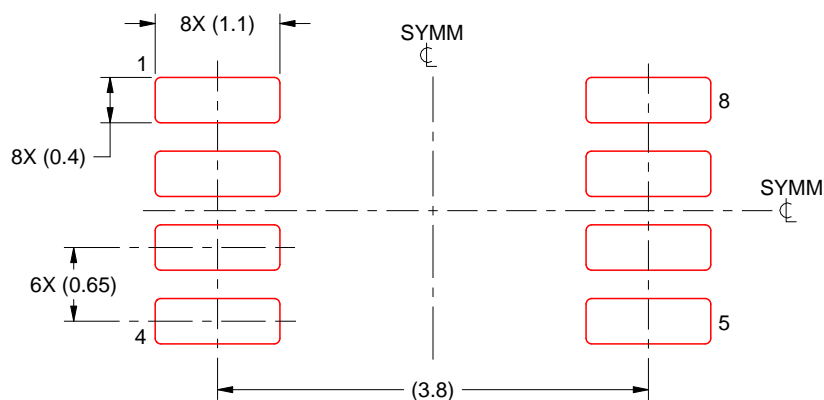
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DCT0008A

SSOP - 1.3 mm max height

SMALL OUTLINE PACKAGE

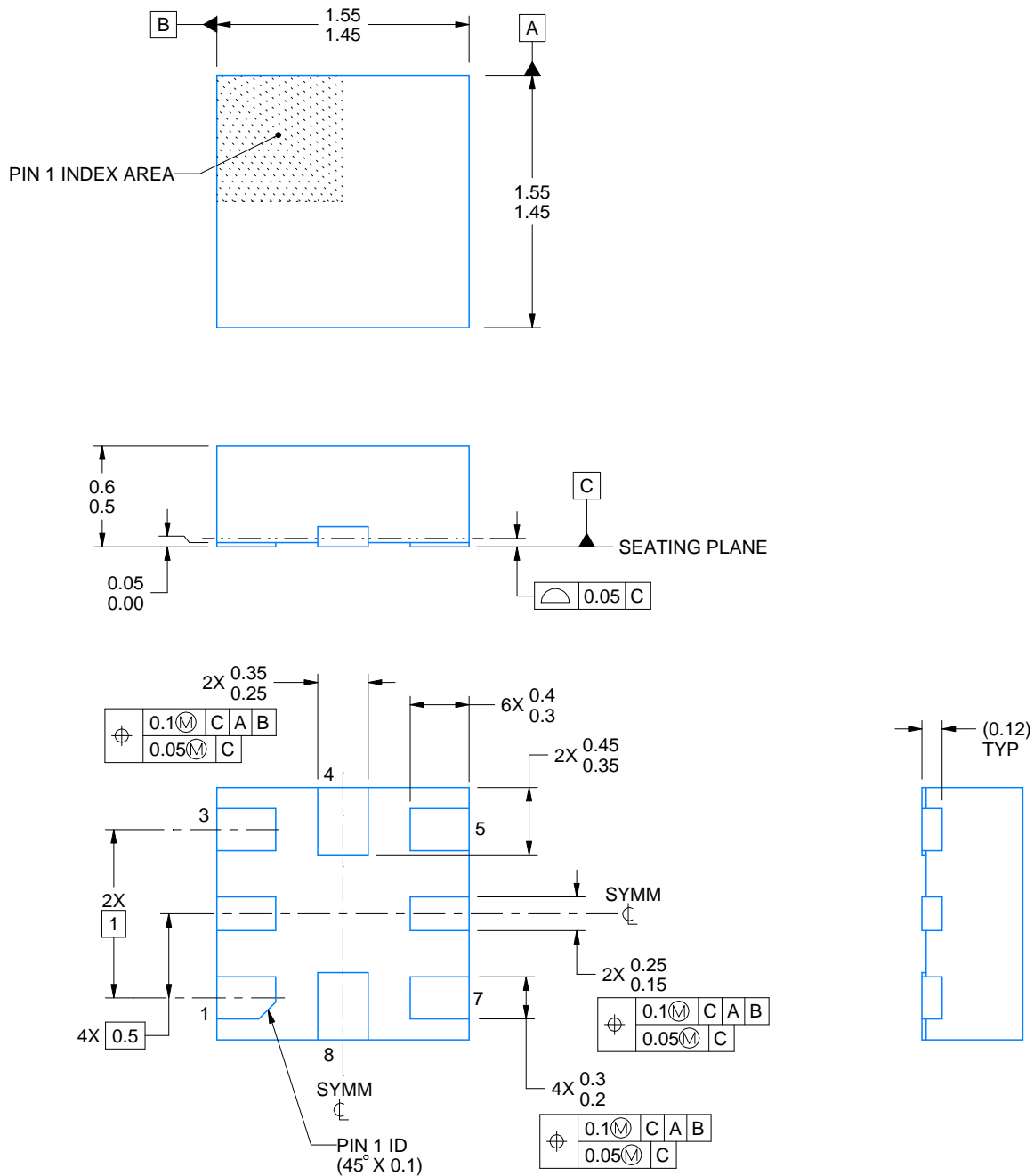


SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

4220784/C 06/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.



4220323/B 03/2018

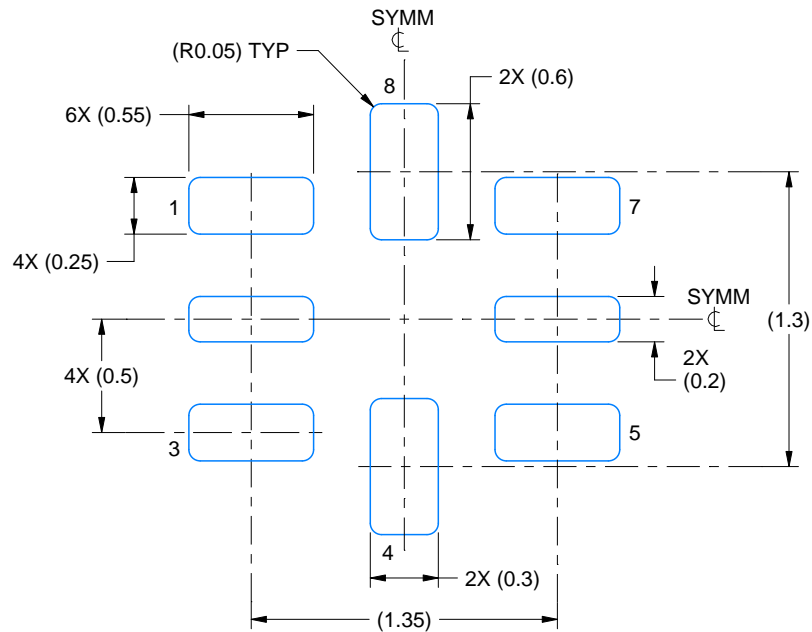
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

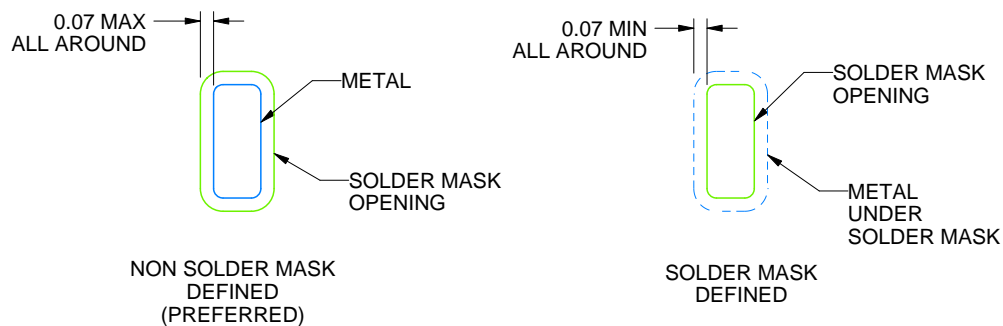
RSE0008A

UQFN - 0.6 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
SCALE:30X



SOLDER MASK DETAILS
NOT TO SCALE

4220323/B 03/2018

NOTES: (continued)

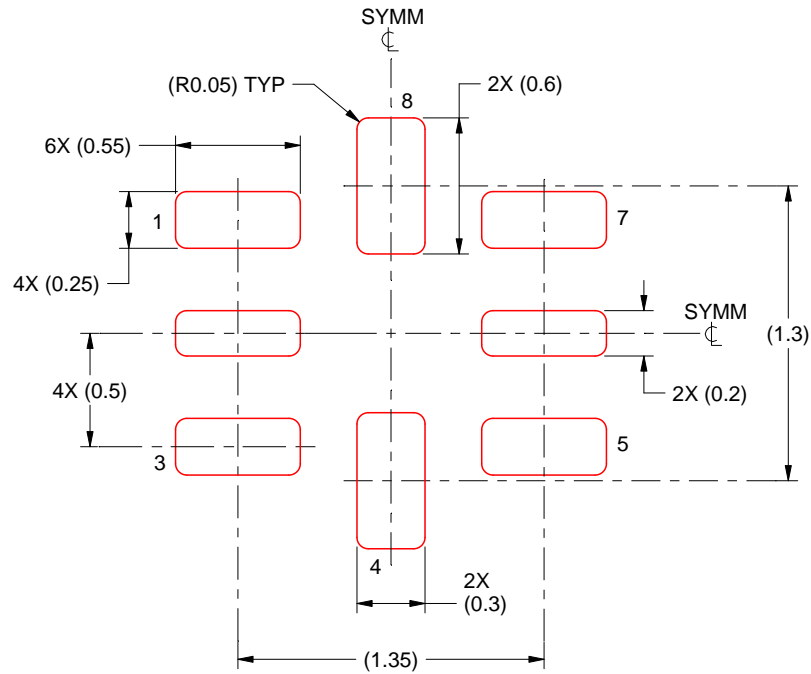
3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sl原因271).

EXAMPLE STENCIL DESIGN

RSE0008A

UQFN - 0.6 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



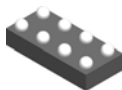
SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICKNESS
SCALE: 30X

4220323/B 03/2018

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

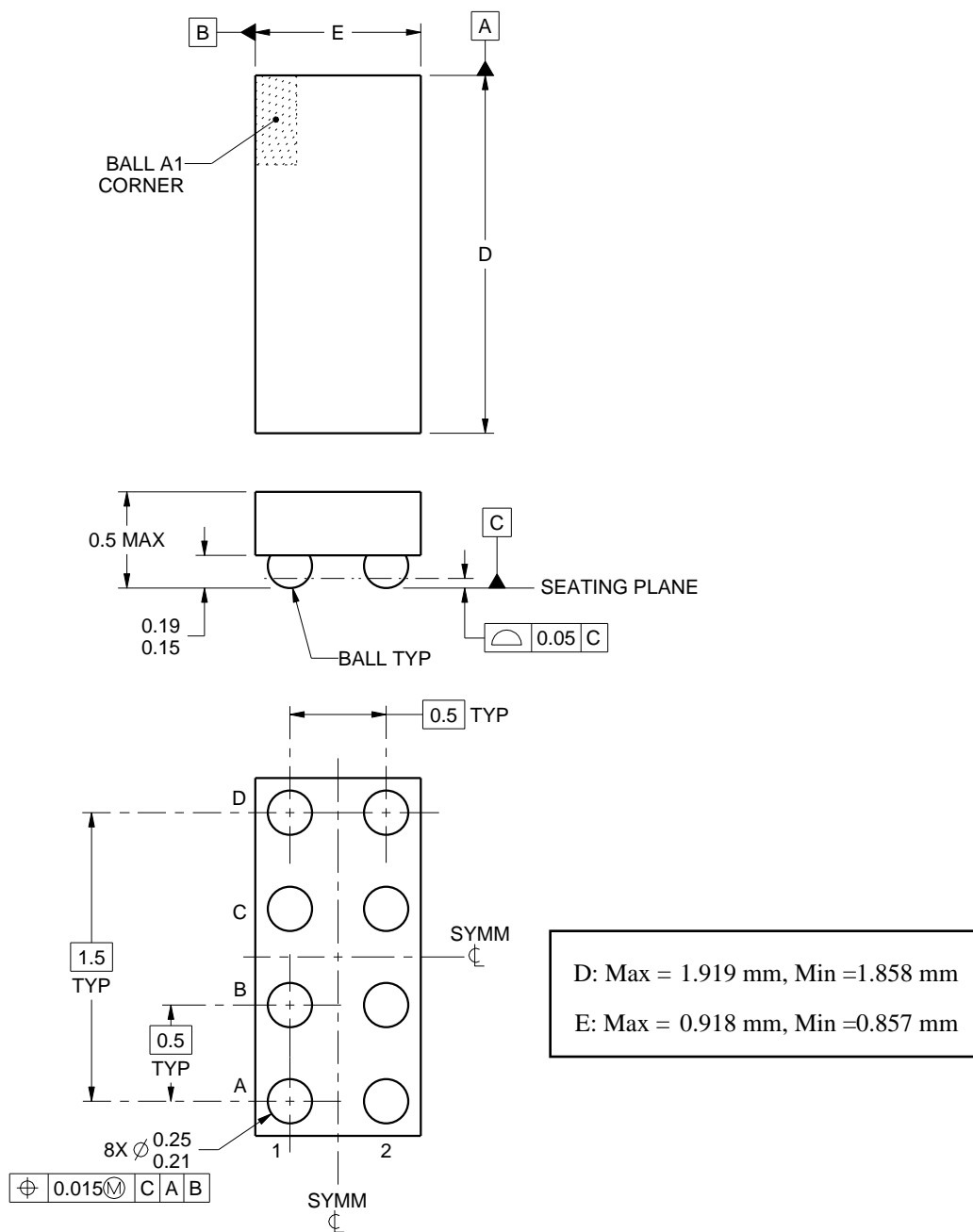
YZP0008



PACKAGE OUTLINE

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



4223082/A 07/2016

NOTES:

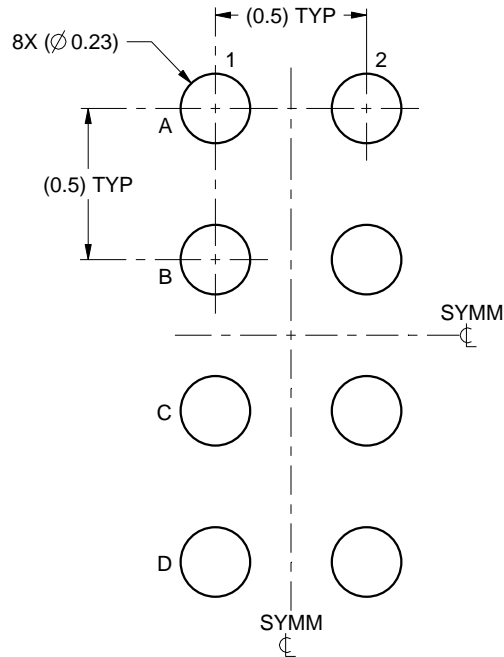
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

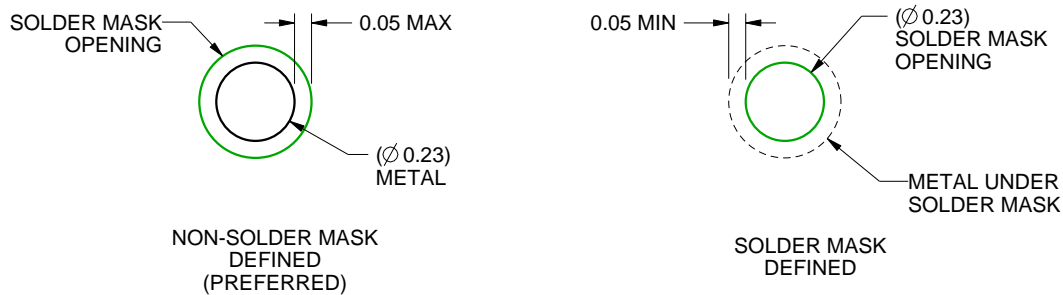
YZP0008

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE
SCALE:40X



SOLDER MASK DETAILS
NOT TO SCALE

4223082/A 07/2016

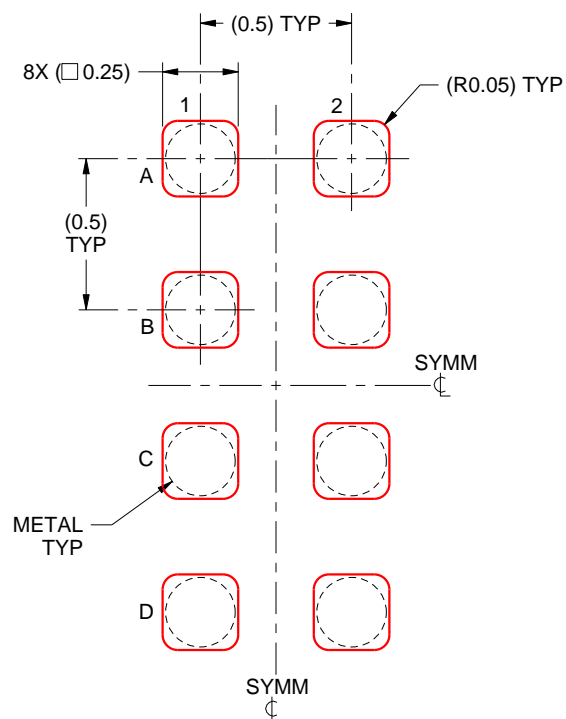
NOTES: (continued)

- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SNVA009 (www.ti.com/lit/snva009).

YZP0008

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:40X

4223082/A 07/2016

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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